

N-Channel Enhancement Mode Power MOSFET

General Description

The YMP200N08 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.

Features

- $V_{DS}=80V$; $I_D=200A@V_{GS}=10V$;
 $R_{DS(ON)} < 3\ m\Omega @ V_{GS}=10V$
- Special process technology for high ESD capability
- Special designed for Convertors and power controls
- High density cell design for ultra low R_{dson}
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

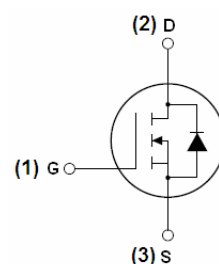
Product Summary

BV_{DSS}	typ.	80	V
$R_{DS(ON)}$	typ.	3	m Ω
	max.	4	m Ω
I_D		200	A

100% UIS TESTED!



TO-247 top view



Schematic diagram

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
YMP200N08	YMP200N08	TO-247	-	-	-

Table 1. Absolute Maximum Ratings (TA=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	80	V
Gate-Source Voltage ($V_{DS}=0V$)	V_{GS}	± 25	V
Drain Current (DC) at $T_c=25^\circ C$	$I_{D(DC)}$	200	A
Drain Current (DC) at $T_c=100^\circ C$	$I_{D(DC)}$	130	A
Drain Current-Continuous@ Current-Pulsed (Note 1)	$I_{DM(pluse)}$	430	A
Maximum Power Dissipation($T_c=25^\circ C$)	P_D	300	W
Derating factor		1.33	W/ $^\circ C$
Single pulse avalanche energy (Note 2)	E_{AS}	2000	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.EAS condition: $T_J=25^\circ C, V_{DD}=28V, V_G=10V, L=1mH, R_g=25\Omega$;

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Note2)	R_{thJC}	0.75	$^{\circ}\text{C}/\text{W}$

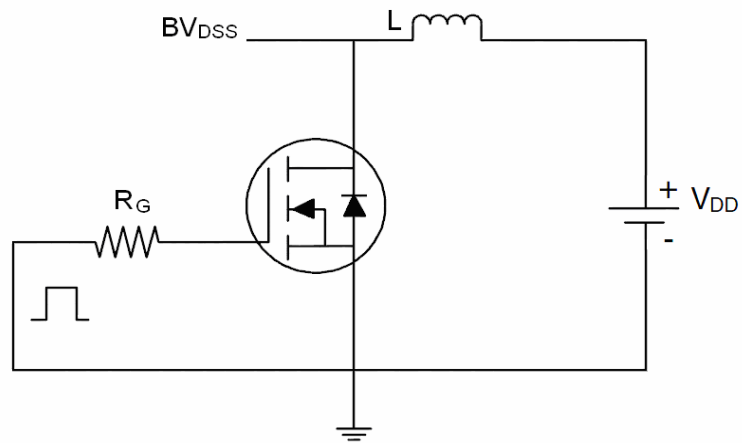
Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	80			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =-24V,V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{DSS}	V _{GS} =±25V,V _{DS} =0V			±100	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	2	-	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =40A		3	4	mΩ
Dynamic Characteristics						
Forward Transconductance	g _{FS}	V _{DS} =25V,I _D =40A	50			S
Input Capacitance	C _{iss}	V _{DS} =30V,V _{GS} =0V, F=1.0MHz		5000		PF
Output Capacitance	C _{oss}			860		PF
Reverse Transfer Capacitance	C _{rss}			480		PF
Total Gate Charge	Q _g	V _{DS} =30V,I _D =40A, V _{GS} =10V		106		nC
Gate-Source Charge	Q _{gs}			20		nC
Gate-Drain Charge	Q _{gd}			35		nC
Switching times						
Turn-on Delay Time	t _{d(on)}	V _{DD} =30V,I _D =1A,R _L =30Ω		34	50	nS
Turn-on Rise Time	t _r			30	46	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G = 4 Ω		124	200	nS
Turn-Off Fall Time	t _f			64	116	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}				40	A
Forward on voltage ^(Note 3)	V _{SD}	T _j =25℃,I _{SD} =20A,V _{GS} =0V		0.8	1.3	V
Reverse Recovery Time ^(Note 1)	t _{rr}	T _j =25℃,I _F =40A,di/dt=100A/μs		74		nS
Reverse Recovery Charge	Q _{rr}			140		nC
Forward Turn-on Time	t _{on}	Intrinsic turn-on time is negligible(turn-on is dominated by L _S +L _D)				

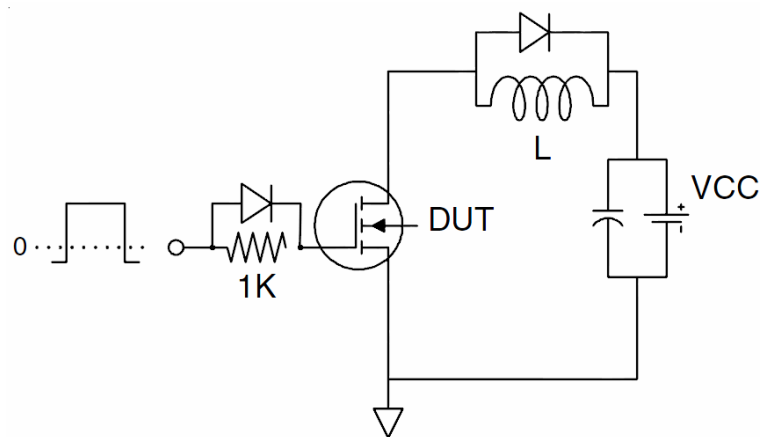
Notes 3.Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$, $R_G=25\Omega$, Starting $T_j=25^{\circ}\text{C}$

Test circuit

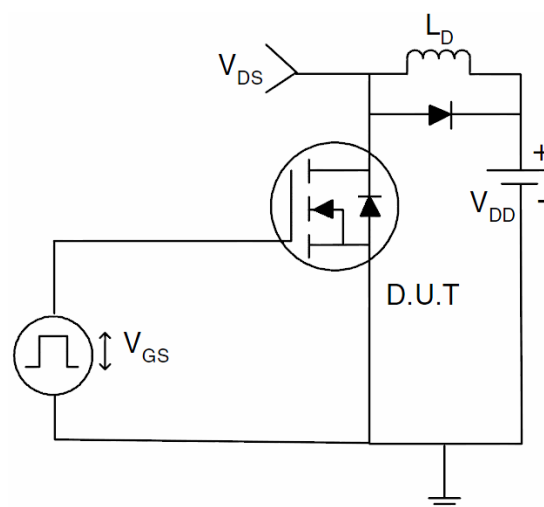
1) E_{AS} test Circuits



2) Gate charge test Circuit:

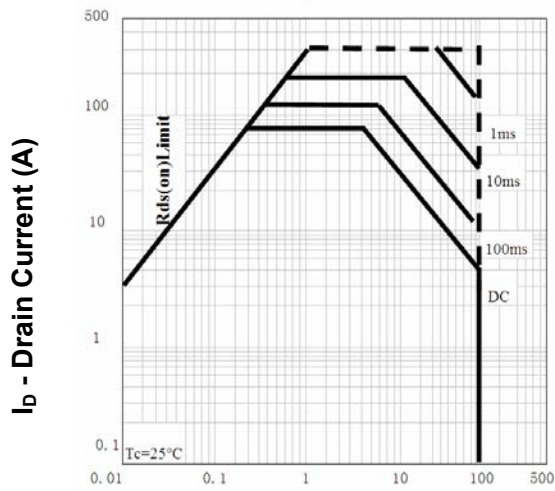


3) Switch Time Test Circuit:



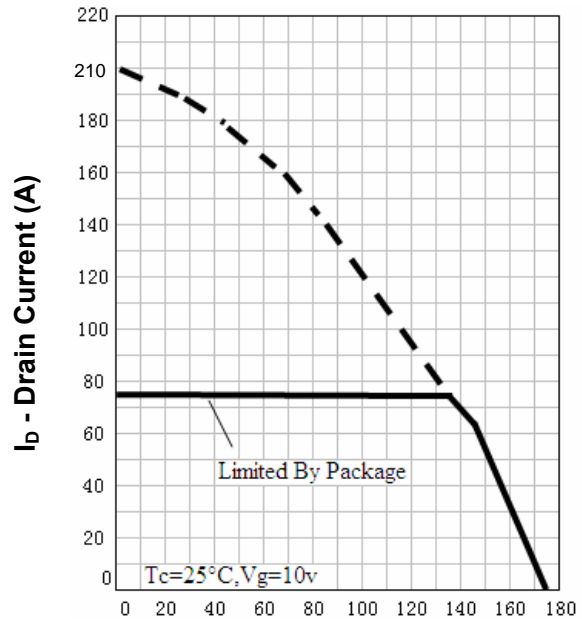
Typical Characteristics

Safe Operation Area



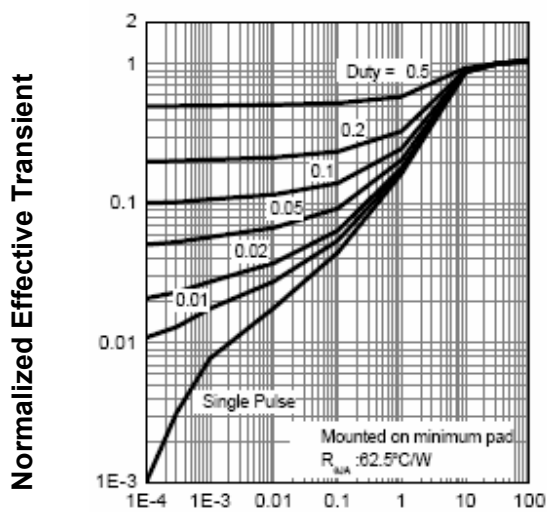
V_{DS} - Drain-Source Voltage (V)

Drain Current



T_J - Junction Temperature ($^\circ\text{C}$)

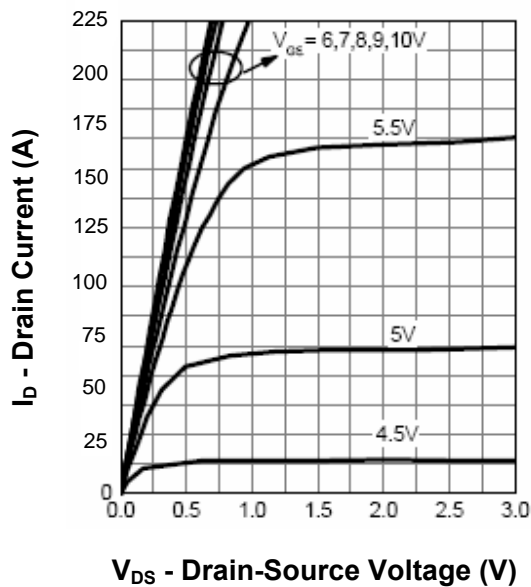
Thermal Transient Impedance



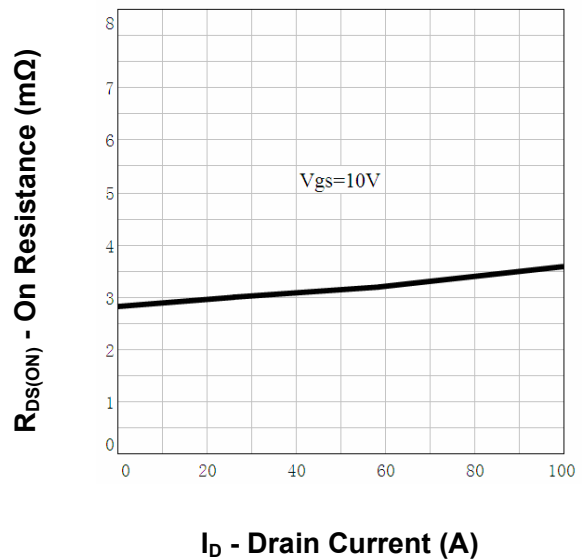
Square Wave Pulse Duration (sec)

Typical Characteristics (Cont.)

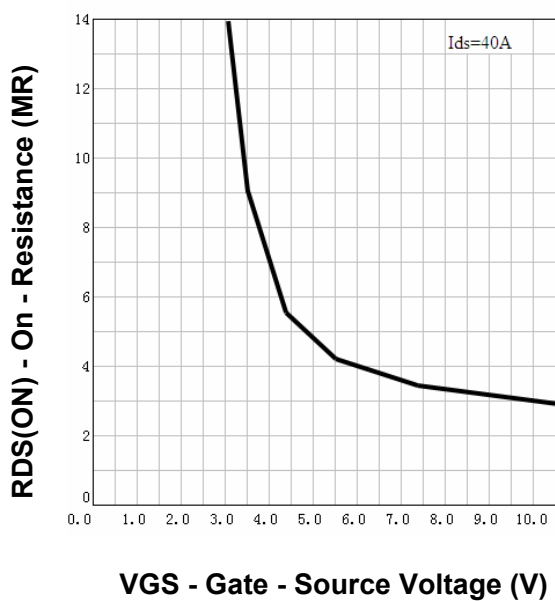
Output Characteristics



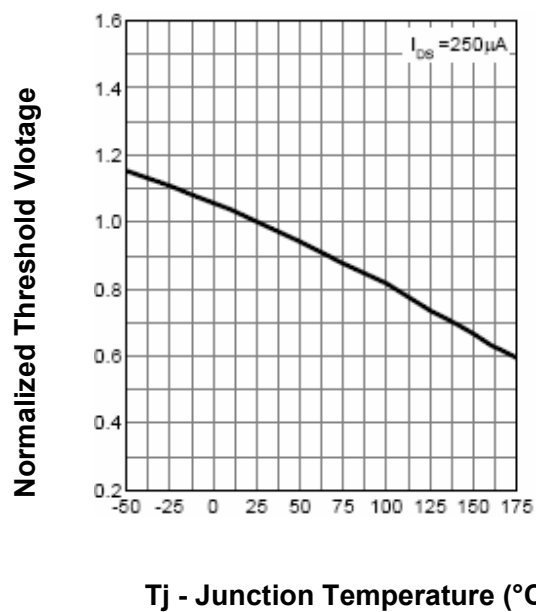
Drain-Source On Resistance



Drain-Source On Resistance

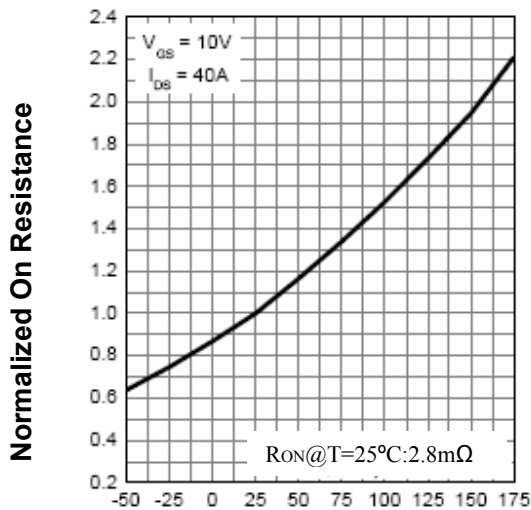


Gate Threshold Voltage



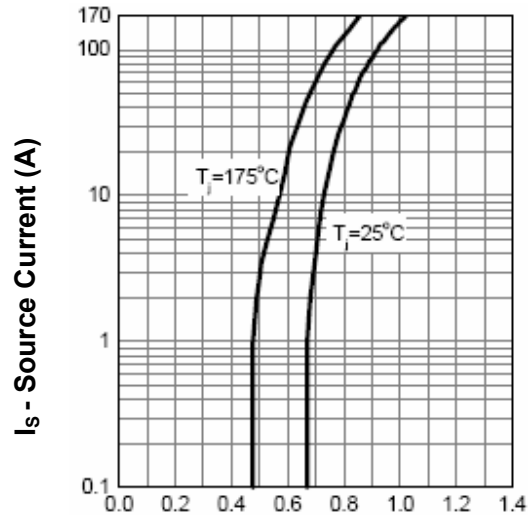
Typical Characteristics (Cont.)

Drain-Source On Resistance



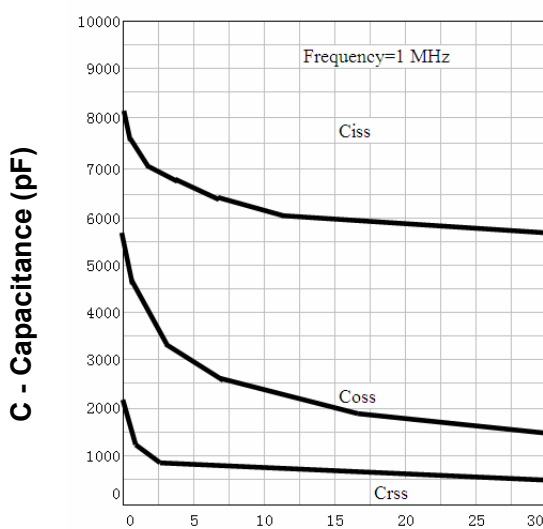
T_j - Junction Temperature (°C)

Source-Drain Diode Forward



V_{SD} - Source-Drain Voltage (V)

Capacitance



V_{DS} - Drain-Source Voltage (V)

Gate Charge

